SN54150, SN54151A, SN54LS151, SN54S151, SN74150, SN74151A, SN74LS151, SN74S151 DATA SELECTORS/MULTIPLEXERS

DECEMBER 1972-REVISED MARCH 1988

- '150 Selects One-of-Sixteen Data Sources
- Others Select One-of-Eight Data Sources
- All Perform Parallel-to-Serial Conversion
- All Permit Multiplexing from N Lines to One Line
- Also For Use as Boolean Function Generator
- Input-Clamping Diodes Simplify System Design
- Fully Compatible with Most TTL Circuits

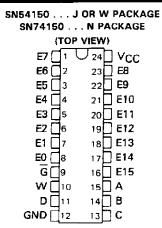
	TYPICAL AVERAGE	TYPICAL
TYPE	PROPAGATION DELAY TIME	POWER
	DATA INPUT TO W OUTPUT	DISSIPATION
150	13 ns	200 mW
151A	8 ns	145 mW
'LS151	13 ns	30 mW
'S151	4.5 ns	225 mW

description

These monolithic data selectors/multiplexers contain full on-chip binary decoding to select the desired data source. The '150 selects one-of-sixteen data sources; the '151A, 'LS151, and 'S151 select one-of-eight data sources. The '150, '151A, 'LS151, and 'S151 have a strobe input which must be at a low logic level to enable these devices. A high level at the strobe forces the W output high, and the Y output (as applicable) low.

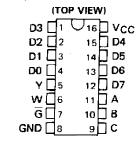
The '150 has only an inverted W output; the '151A, 'LS151, and 'S151 feature complementary W and Y outputs.

The '151A and '152A incorporate address buffers that have symmetrical propagation delay times through the complementary paths. This reduces the possibility of transients occurring at the output(s) due to changes made at the select inputs, even when the '151A outputs are enabled (i.e., strobe low).

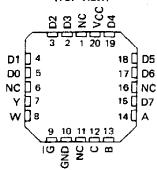


SN54151A, SN54LS151, SN54S151 . . . J OR W PACKAGE SN74151A . . . N PACKAGE

SN74LS151, SN74S151 . . . D OR N PACKAGE



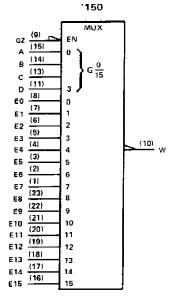
SN54LS151, SN54S151 . . . FK PACKAGE (TOP VIEW)

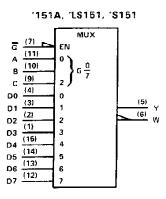


NC - No internal connection

SN54150, SN54151A, SN54LS151, SN54S151, SN74150, SN74151A, SN74LS151, SN74S151 DATA SELECTORS/MULTIPLEXERS

logic symbols†





'150 FUNCTION TABLE

		INI	PUT	S	OUTPUT
	SEL	ECT	•	STROBE	w
D	С	В	_A	Ğ	VV
Х	X	Х	Х	Н	Ŧ
L	L	L	L	L	ΕÖ
L	L	L	H	L	E1
L	L	H	L	L	E2
L	L	Н	н	L	Ē3
L	Н	L	L	L,	Ē4
L	н	L	Η :	L	E5
L	н	Н	L.	Ļ	<u>E6</u>
L	н	Н	н	L	E7
н	L	L	Ł	L	€8
Н	L	L	Н	L	Ē9
Н	L	н	L	L	E10
н	L	Н	н	L	E11
н	н	L	L	L	E12
н	Н	L	н	L	E13
н	Н	Н	L	L	E14
н	н	н	н	L	E15

'151A, 'LS151, 'S151 FUNCTION TABLE

	11	VPUT	S	OUT	PUTS
S	ELEC	T	STROBE	v	w
C	В	Α	Ğ	*	**
Х	Х	Х	Н	L	I
L	L	L	L	DO	<u>500</u>
L	L	Н	L	D1	D1
L	Н	L	L	D2	D2
L	н	Н	L	D3	D3
Н	L	L	L	D4	D4
Н	L	H	L	D5	D5
Н	н н Ļ		L	D6	D6
Н	Н	н	L	D7	D7

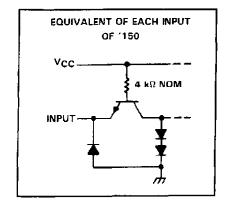
H = high level, L = low level, X = irrelevant

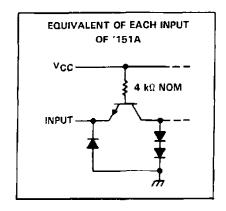
 $\overline{\text{E0}}$, $\overline{\text{E1}}$. . . $\overline{\text{E15}}$ = the complement of the level of the respective E input

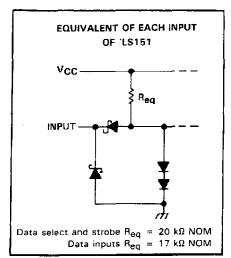
DO, D1 . . . D7 = the level of the D respective input

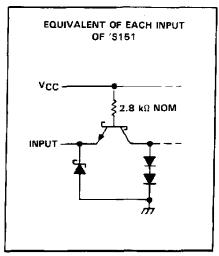
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are D, J, N, and W packages.

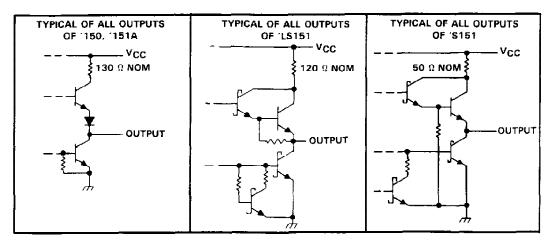
schematics of inputs and outputs











SN54150, SN54151A, SN74150, SN74151A DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

		SN54'			SN74'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH		-	-800			-800	μА
Law-level output current, IOL			16			16	mΑ
Operating free-air temperature, TA	-55		125	0		70	C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	CA CAMPTED	TEST CONDI	TIONST		1150			151A		UNIT
	PARAMETER 	TEST CONDI	TIONS.	MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	UNII
VιΗ	High-level input voltage			2			2			٧
VIL	Low-level input voltage			•		0.8			0.8	٧
VIK	Input clamp voltage	VCC = MIN. I	= -8 mA			- 1.5			-1.5	V
∨он	High-level output voltage	$V_{CC} = MIN, V_{H}$ $V_{IL} = 0.8 \text{ V}, I_{OI}$	· 1	2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage	$V_{CC} = MIN, V_{II}$ $V_{IL} = 0.8 \text{ V}, I_{OI}$			0.2	0.4		0.2	0.4	٧
l _j	Input current at maximum input voltage	VCC = MAX, V	= 5.5 V			1 ,			1	mΑ
lite	High-level input current	VCC = MAX, VI	= 2.4 V			40			40	μА
l _{IL}	Low-level input current	$V_{CC} = MAX, V_I$	= 0.4 V		·	-1.6			-1.6	mA
		14 MAN	SN54'	- 20		- 55	- 20		- 55	
los	Short-circuit output current ⁹	V _{CC} = MAX	SN74'	- 18		- 55	-18		- 55	mA
lcc	Supply current	V _{CC} = MAX, See	Note 3		40	68		29	48	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

switching characteristics, VCC = 5 V, TA = 25°C

	FROM	то	TEST	,	150			151/	4	
PARAMETER ¶	(INPUT)	(OUTPUT)	CONDITIONS	MIN 7	TYP	MAX	MIN	TYP	MAX	UNIT
tPLH	A, B, or C	Y						25	38	
[†] PHL	(4 levels)] '						25	38	пş
tPLH	A, B, C, or D	w			23	35		17	26	ns
^t PHL	(3 levels)	,			22	33		19	30	1115
tPLH	Strobe G	Y	Cլ = 15 թF,					21	33	ns
tPHL .	Strone G		$R_L = 400 \Omega$					22	33	1115
tPLH	Strobe \vec{G}	w	See Note 4	1	5.5	24		14	21	ns
tPH L	Strope G	**	200 17013 17		21	30		15	23	,''\$
†PLH	DO thru D7	Y						13	20	
₹PHL	Bo till a D							18	27	ns
tPLH	E0 thru E15, or	W			8.5	14		8	14	
tPHL .	D0 thru D7				13	20		8	14	ns

 $f_{\text{tpLH}} = \text{propagation delay time, low-to-high-level output}$ $t_{\text{pHL}} = \text{propagation delay time, high-to-low-level output}$

[†] All typical values at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

Not more than one output of the '151A should be shorted at a time.

NOTE 3: ICC is measured with the strobe and data select inputs at 4.5 V, all other inputs and outputs open.

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	S	N54LS	151	Si	N74LS1	51	LINICT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	b,b	4.75	5	5.25	٧
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			4			8	mA
Operating free-air temperature, TA	-65		125	0		70	C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAGAMETEO	TEST CONDIT	unant.	s	N54LS1	51	s	N74LS1	51	UNIT
	PARAMETER	TEST CONDIT	IONS.	MIN	ΤΥ₽ [‡]	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			2			٧
VIL	Low-level input voltage					0.7			0.B	٧
Vik	Input clamp voltage	V _{CC} - MIN, I _f = -1	8 mA			- 1.5			-1.5	٧
Vон	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V _{IL} = V _{IL} max, I _{OH} =		2.5	3.4		2.7	3.4		٧
VoL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V _{II} = V _{II} max	2 V, I _{OL} = 4 mA I _{OL} = 8 mA		0.25	0.4		0.25 0.35	0.4 0.5	٧
Ιţ	Input current at maximum input voltage	$V_{CC} = MAX$, $V_1 = 7$				0.1			0.1	mA
ЧН	High-level input current	$V_{CC} = MAX$, $V_1 = 2$.	7 V			20			20	μΑ
IIL	Low-level input current	$V_{CC} = MAX$, $V_{I} = 0$.	4 V			-0.4			-0.4	mA
los	Short-circuit output current§	V _{CC} = MAX		- 20		- 100	- 20		- 100	mΑ
lcc	Supply current	V _{CC} = MAX, Outputs All inputs at 4.5 V	open,		6.0	10		6.0	10	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

switching characteristics, VCC = 5 V, TA 25 °C

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
[†] PLH	A, B, or C	Y			27	43	
tPHL	(4 levels)	ı .			18	30	ns
tPLH	A, B, or C	W	1		14	23	
tPHL	(3 levels)				20	32	ns
^t PLH	Strobe G	Y	0. 15.5		26	42	
t _{PHL}	2 strope G	irobe d	C _L = 15 pF,		20	32	ns
[†] PLH	Strobe G	W	R _L = 2 kΩ,		15	24	
tpHL	Strope G	W See Note 4	18	30	ns		
t _{PLH}]		20	32	
tpHL	Any D	Y	İ		16	26	ns
tPLH	A D	w			13	21	
[†] PHL	Any D	vv			12	20	ns



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. $^{\$}$ Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

[¶]tpLH = propagation delay time, low-to-high-level output tpHL = propagation delay time, high-to-low-level output NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

SN54S151, SN74S151 DATA SELECTORS/MULTIPLEXERS

recommended operating conditions

	S	N54S1	51		N74S1	51	
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH		_	-1			-1	mA
Low-level output current, IOL			20			20	πА
Operating free-air temperature, TA	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONST		MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
Vik	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA				-1.2	V
· · · · ·	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V,	SN54S151	2.5	3.4		
νон	riign-rever ou tout vortage	VIL = 0.8 V, IOH = -1 mA	SN74S151	2.7	3.4		٧
VOL	Low-level output voltage	VCC = MIN, VIH = 2 V,	-			0.5	v
VOL	Low-level output voltage	V _{IL} = 0.8 V, I _{OL} = 20 mA	i			0.5	v
l _k	Input current at maximum input voltage	VCC = MAX, V1 = 5.5 V				1	mA
ΉН	High-level input current	V _{CC} = MAX, V _I = 2.7 V				50	μА
1 _{IL}	Low-level input current	V _{CC} - MAX, V _I = 0.5 V				-2	mA
los	Short-circuit output current 8	V _{CC} = MAX		-40		-100	mA
¹cc	Supply current	VCC = MAX, All inputs at 4.5 V,			45	70	mA
		All outputs open	Ī		. •		,

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device

switching characteristics. V_{CC} = 5 V. T_A 25 °C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	A, B, or C	Y	•		12	18	
^t PHL	(4 levels)	ţ	ļ		12	18	ns
tPLH	A, B, or C	w	1		10	15	
[†] PHL	(3 levels)				9	13.5	ns
tPLH	Any D	Y	G 45-5		8	12	
₹PHL	Any	,	C _L = 15 pF,		8	12	ns
tpLH	Any D	W	R _L = 280 kΩ, See Note 4		4.5 4.5	7	ns
tPHL	T ANY D	VV	See Note 4			7	
tpLH	Strobe G	Y			11	16.5	
tpHL	3trope G	т			12	18	ns
^t PLH	Strobe G	w			9	13	
tPHL	Strope G				8.5	12	กร

TtpLH = propagation delay time, low-to-high-level output



 $[\]ddagger$ All typical values are at \lor CC = 5 \lor , \lnot A = 25°C. \ddagger Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

tpHL - propagation delay time, high-to-low-level output
NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

5-Sep-2011

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9558001QJA	ACTIVE	CDIP	J	24	1	TBD	Call TI	Call TI	
5962-9558001QKA	ACTIVE	CFP	W	24	1	TBD	Call TI	Call TI	
5962-9558001QKA	ACTIVE	CFP	W	24	1	TBD	Call TI	Call TI	
5962-9751601Q2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
5962-9751601QCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
5962-9751601QDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	
76010012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
76010012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
7601001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7601001EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7601001FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
7601001FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
JM38510/01401BKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
JM38510/01401BKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
JM38510/07901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30901B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30901BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SN54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SN54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SN54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S15J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74150N	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74150N	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	



5-Sep-2011

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74150NE4	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74150NE4	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74151AN	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74151AN	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS151J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
SN74LS151N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS151N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	



www.ti.com 5-Sep-2011

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS151NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS151NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S151N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S151N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S151N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S151N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S151NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S151NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SNJ54150J	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
SNJ54150W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
SNJ54150W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS151W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	·
SNJ54S151J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S151W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	



www.ti.com 5-Sep-2011

Orderable Device	Status (1) F	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54S15FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
SNJ54S15J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SNJ54S15W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54150, SN54LS151, SN54S15, SN54S151, SN74150, SN74LS151, SN74S151:

Catalog: SN74150, SN74LS151, SN74S15, SN74S151

Military: SN54150, SN54LS151, SN54S151

NOTE: Qualified Version Definitions:



5-Sep-2011

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 29-Jul-2009

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS151DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS151NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 29-Jul-2009



*All dimensions are nominal

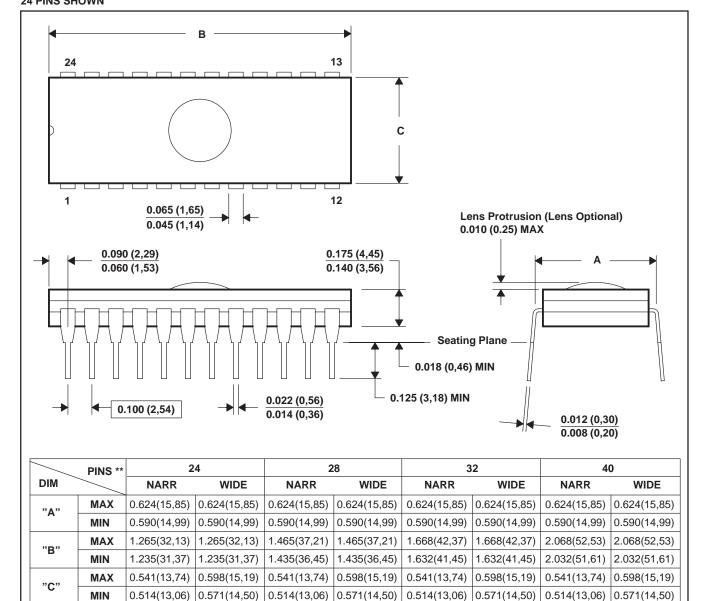
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS151DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS151NSR	SO	NS	16	2000	346.0	346.0	33.0

4040084/C 10/97

J (R-GDIP-T**)

24 PINS SHOWN

CERAMIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
- D. This package can be hermetically sealed with a ceramic lid using glass frit.
- E. Index point is provided on cap for terminal identification.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

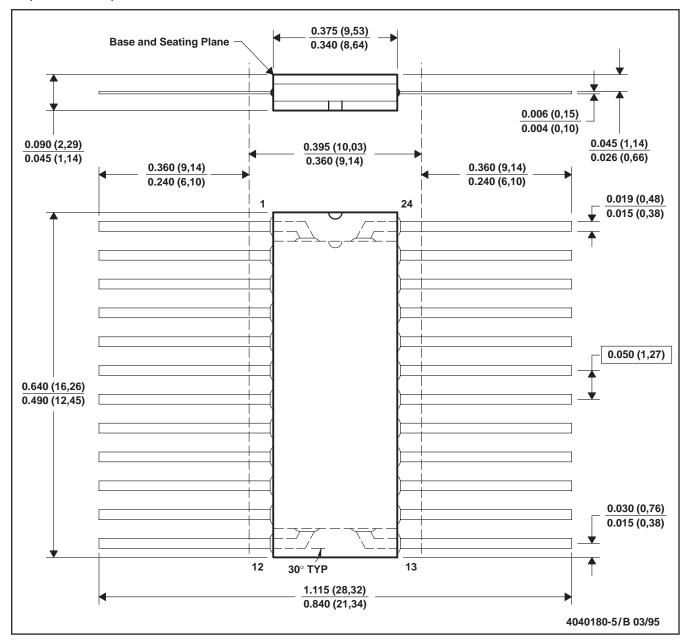


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
 - E. Index point is provided on cap for terminal identification only.



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

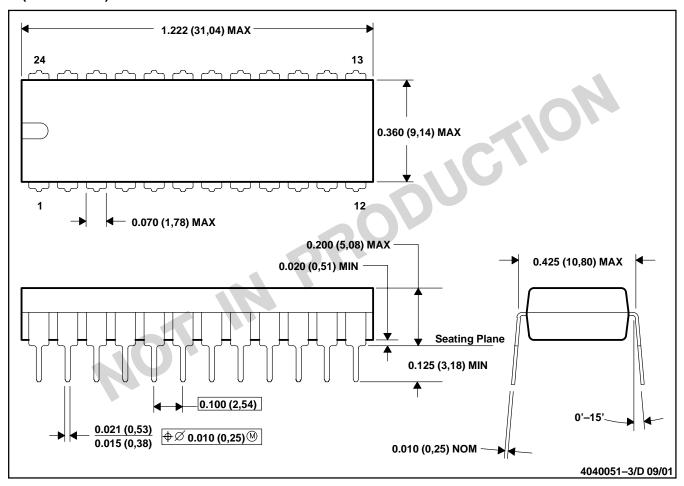


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



N (R-PDIP-T24)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-010

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-011
- D. Falls within JEDEC MS-015 (32 pin only)



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications

interface.ti.com

Audio www.ti.com/audio Communications and Telecom www.ti.com/communications **Amplifiers** amplifier.ti.com Computers and Peripherals www.ti.com/computers dataconverter.ti.com Consumer Electronics www.ti.com/consumer-apps **Data Converters DLP® Products** www.dlp.com **Energy and Lighting** www.ti.com/energy DSP dsp.ti.com Industrial www.ti.com/industrial Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical

Logic logic.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Security

Power Mgmt power.ti.com Transportation and Automotive www.ti.com/automotive

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID <u>www.ti-rfid.com</u>

OMAP Mobile Processors www.ti.com/omap

Interface

Wireless Connctivity www.ti.com/wirelessconnectivity

TI E2E Community Home Page <u>e2e.ti.com</u>

www.ti.com/security